

ON Semiconductor				9/20/2020
Base Part		MOC3073M		Pb-free
Orderable Part		MOC3073SVM		Total weight (mg) 458.02
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Coupling Gel	168.9	Dimethyl Cyclosiloxanes	69430-24-6	10
		Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3	90
Die	5.13	Silicon (Si)	7440-21-3	100
Die Attach	0.24	Silver (Ag)	7440-22-4	75
		Phenolic Resin-2	54208-63-8	25
Lead Frame	62.28	Silver (Ag)	7440-22-4	0.71
		Zinc (Zn)	7440-66-6	0.12
		Iron (Fe)	7439-89-6	2.35
		Copper (Cu)	7440-50-8	96.79
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-White	220.75	Titanium Dioxide (TiO2)	13463-67-7	25
		Brominated Bisphenol A Diglycidyl Ether	40039-93-8	3
		Ortho Cresol Novolac Resin	29690-82-2	13.5
		Antimony Trioxide (Sb2O3)	1309-64-4	3
		Fused Silica (SiO2)	60676-86-0	50
Plating	0.36	Phenolic Resin (Novolac)	9003-35-4	5.5
Wire Bond - Au	0.36	Tin (Sn)	7440-31-5	100
		Gold (Au)	7440-57-5	100
<p><b>Materials Disclosure Disclaimer:</b> Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at: <a href="https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF">https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</a></p>				